ABSTRACT

An integrated circuit including an inductive element according to some embodiments is provided. The inductive element includes a first through electrode extending in a first direction that is perpendicular to a substrate (e.g., an upper surface of the substrate), an upper metallization pattern connected to the first through electrode and extending in a second direction that is perpendicular to the first direction, and a lower metallization pattern connected to the first through electrode and extending in the second direction, wherein the upper metallization pattern and the lower metallization pattern are spaced apart from each other with the first through electrode therebetween.

FIG. 1B